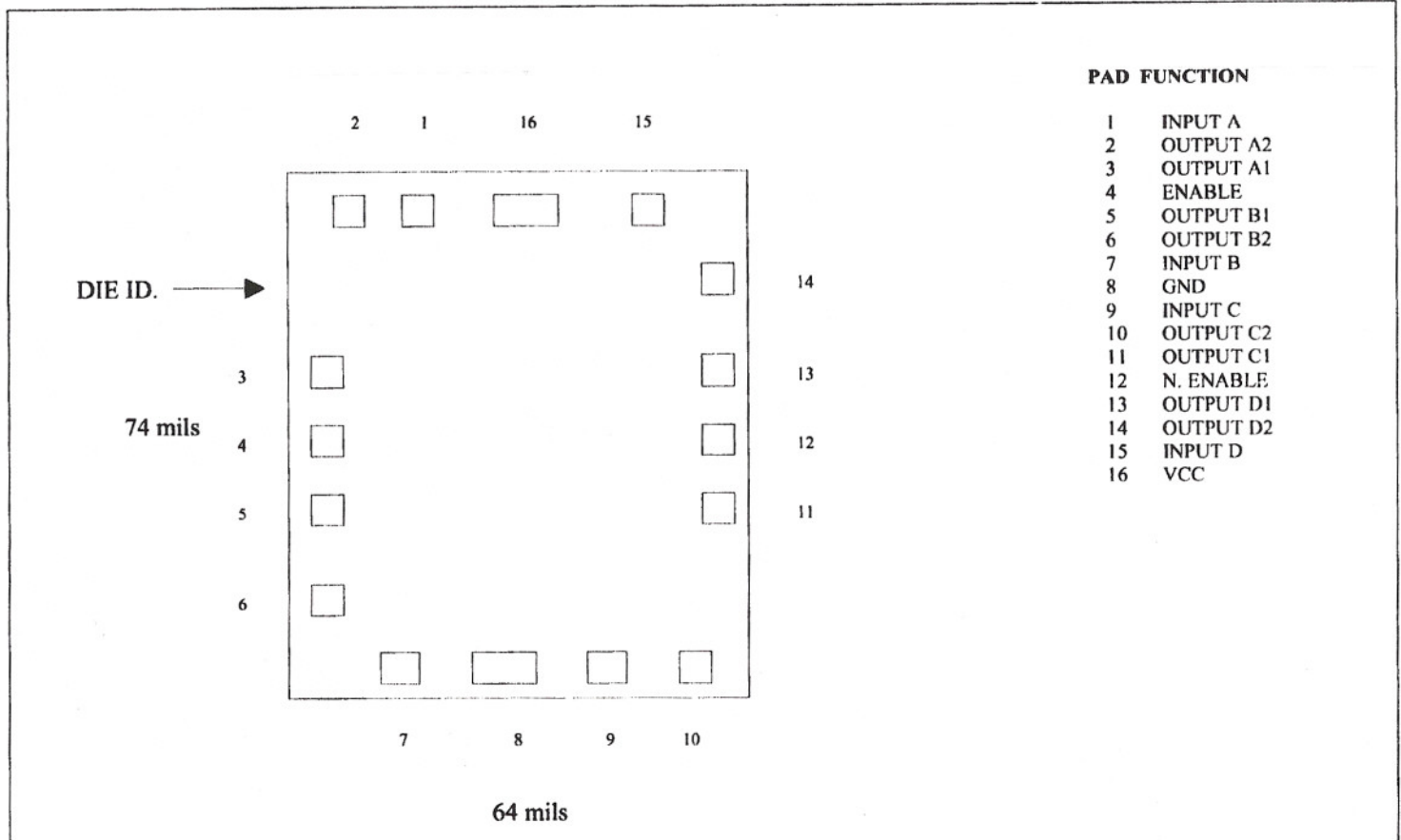




Sierra Components, Inc.

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PAD FUNCTION

- 1 INPUT A
- 2 OUTPUT A2
- 3 OUTPUT A1
- 4 ENABLE
- 5 OUTPUT B1
- 6 OUTPUT B2
- 7 INPUT B
- 8 GND
- 9 INPUT C
- 10 OUTPUT C2
- 11 OUTPUT C1
- 12 N. ENABLE
- 13 OUTPUT D1
- 14 OUTPUT D2
- 15 INPUT D
- 16 VCC

NOTE: Chip must be connected to GND

The information given is believed to be correct at the time of issue.
 Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
 Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

<p><u>APPROVED</u></p> <p>D Markham</p> <p>.....</p> <p>DATE: 15/8/00</p>	<p>DS26C31C</p> <p>NATIONAL SEMICONDUCTOR</p>	<p><u>DIE INFORMATION</u></p> <p>DIMENSIONS (Mils): 64 x 74 x 15</p> <p>BOND PADS (Mils): 4 x 4</p> <p>MASK. REF:</p> <p>GEOMETRY:</p> <p>BACK POTENTIAL: GND</p>
<p><u>SERIAL NUMBER.</u></p> <p>004245</p>		<p><u>METALLISATION</u></p> <p>TOP: Al</p> <p>BACK: Si</p>